	draw_stackup_E_Paste.gtp draw_stackup_E_Silkscreen.gto draw_stackup_E_Cu.gtl draw_stackup_In1_Cu.g2 draw_stackup_In2_Cu.g3 draw_stackup_B_Cu.gbl draw_stackup_B_Mask.gbs draw_stackup_B_Silkscreen.gbo	1.6 mm	Top Solder Paste Top Silk Screen: Whit Top Solder Mask: Gre Copper (35 µm/1 oz Prepreg 21116 100 µ Copper (35 µm/1 oz CORE FR4 1240 µm Copper (35 µm/1 oz Prepreg FR4 100 µm Copper (35 µm/1 oz Bottom Solder Mask Bottom Silk Screen
dra	draw_stackup_B_Silkscreen.gbo		
	draw_stackup_B_Paste.gbp		Bottom Solder Paste

op Solder Paste op Silk Screen: White Direct Printing op Solder Mask: Green Epoxy ϵ_r 3.3 Copper (35 µm/1 oz) Prepreg 21116 100 µm Copper (35 µm/1 oz) CORE FR4 1240 μ m ϵ_{r} 4.5 $tan\delta$ 0.02 Copper (35 µm/1 oz) Prepreg FR4 100 μ m ϵ_r 4.5 $tan\delta$ 0.02 Copper (35 µm/1 oz) Bottom Solder Mask Bottom Silk Screen